

HSB124S

Silicon Epitaxial Planar Diode for High Speed Switching

REJ03G0547-0200

(Previous: ADE-208-488A)

Rev.2.00 Mar 04, 2005

Features

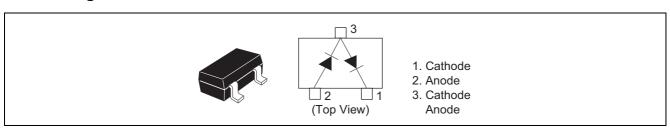
• Low reverse current. ($I_R = 0.01 \mu A \text{ max}$)

• CMPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HSB124S	A1	CMPAK	PTSP0003ZB-A (CMPAK)

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Peak reverse voltage	V_{RM}	85	V
Reverse voltage	V _R	80	V
Peak forward current	I _{FM} * ¹	300	mA
Non-Repetitive peak forward surge current	I _{FSM} * ²	4	Α
Average rectified current	Io *1	100	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Notes: 1. Two device total.

2. Value at duration of 1 μ s, two device total.

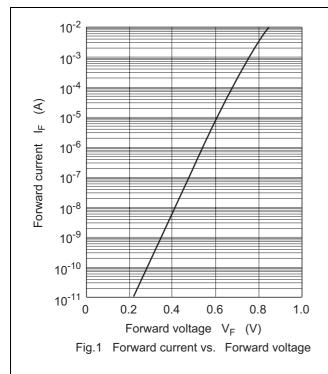
Electrical Characteristics *

 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V _F	_	_	1.2	V	I _F = 100 mA
Reverse current	I _R	_	_	0.01	μΑ	V _R = 80 V
Capacitance	С	_	_	4.0	pF	V _R = 0 V, f = 1 MHz
Reverse recovery time	t _{rr}	_	_	100	ns	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}, R_L = 50 \Omega$

Note: Per one device.

Main Characteristic



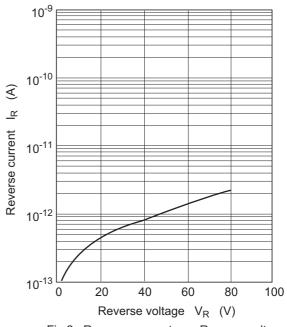
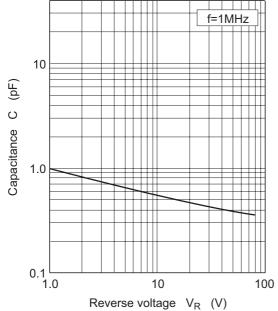
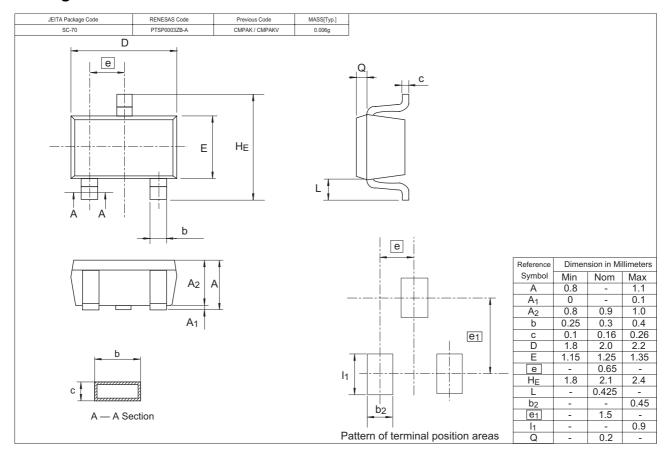


Fig.2 Reverse current vs. Reverse voltage



Package Dimensions



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